

File No. 14836-9US AD/mg

Montréal, CANADA,  
August 6, 2008

**UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No : 10/532,627  
Filing Date : April 25, 2005  
Applicant : Microbridge Technologies Inc.  
Inventor : Leslie M. Landsberger et al.  
Title of Invention : METHOD FOR PRODUCING A PACKAGED INTEGRATED CIRCUIT  
Classification : 2822  
Examiner : David E. Graybill Tel: (571) 272-1930  
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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
USA

**RESPONSE**

Sir:

In response to the Office Action dated May 15, 2008 in connection with the above-identified Application, please consider the following:

**Amendments to the claims** begin on page 2 of this paper.

**Remarks** begin on page 8 of this paper.